

AMENDMENTS TO THE SPECIFICATION

Please amend the specification as described below:

- Please amend the paragraph which begins on page 7, line 19, as follows:

Accordingly, the heat sink 600 can provide support for a die that is larger than the first die 504 if necessary or desirable for a particular design. The heat sink 600 has a path to a ground plane-604 610 formed, for example, by providing an electrically conductive material layer 608 on its surface, such as by plating the electrically conductive material onto the heat sink 600.

- Please amend the paragraph which begins on page 7, line 24, as follows:

In the embodiment shown in FIGs. 5-8, the heat sink 600 has an electrically conductive surface-material layer 608 that is formed, for example, by plating an electrically conductive material, such as silver, on the surface of the heat sink 600. The heat sink 600 therefore can provide a ground plane for the second die 700 if necessary for a particular design.

- Please amend the paragraph which begins on page 8, line 17, as follows:

A first ground wire 706 is connected between the second die 700 and the electrically conductive material layer 608 on heat sink 600. ~~The heat sink 600 electrically conductive material layer 608~~, in turn, is connected to the ground plane 610 on the substrate 502 by a second ground wire 708. The second die 700 therefore is electrically connected to the ground plane 610 on the substrate 502 through the first ground wire 706, ~~the heat sink 600 electrically conductive material layer 608~~, and the second ground wire 708. The first ground wire 706 and the second ground wire 708 also provide a path for heat to be conducted away from the heat sink 600 to the substrate 502.